

FEATURES

- 10µs Short Circuit Withstand
- Non Punch Through Silicon
- Isolated Copper Baseplate

APPLICATIONS

- Choppers
- Motor Controllers
- Induction Heating
- Resonant Converters
- Power Supplies

The Powerline range of high power modules includes half bridge, chopper, dual, single and bi-directional switch configurations covering voltages from 600V to 3300V and currents up to 2400A.

The DIM200MKS12-A000 is a 1200V, n channel enhancement mode, insulated gate bipolar transistor (IGBT) chopper module configured with the upper arm of the bridge controlled. The module incorporates a high current rated freewheel diode. The IGBT has a wide reverse bias safe operating area (RBSOA) plus full 10µs short circuit withstand.

The module incorporates an electrically isolated base plate and low inductance construction enabling circuit designers to optimise circuit layouts and utilise grounded heat sinks for safety.

ORDERING INFORMATION

Order As:

DIM200MKS12-A000

Note: When ordering, please use the whole part number.

KEY PARAMETERS

| | | |
|-----------------|--------------|--------------|
| V_{CES} | | 1200V |
| $V_{CE(sat)}$ * | (typ) | 2.2V |
| I_C | (max) | 200A |
| $I_{C(PK)}$ | (max) | 400A |

*(measured at the power busbars and not the auxiliary terminals)

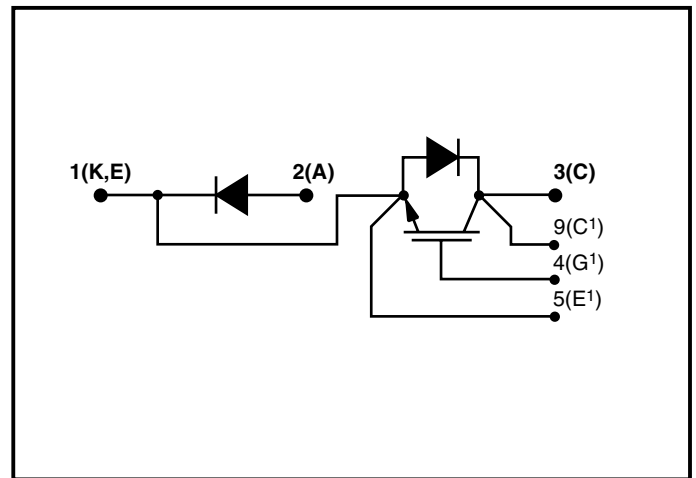


Fig. 1 Chopper circuit diagram - upper arm controlled

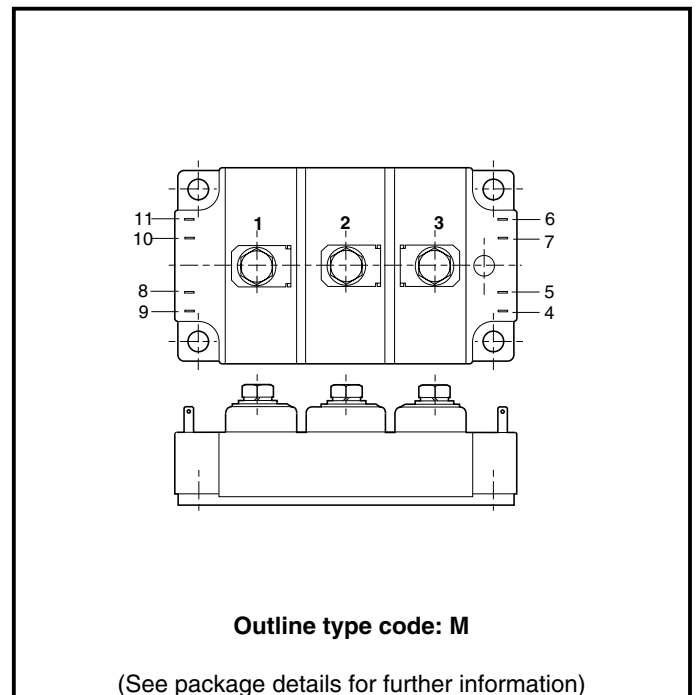


Fig. 2 Electrical connections - (not to scale)

ABSOLUTE MAXIMUM RATINGS - PER ARM

Stresses above those listed under 'Absolute Maximum Ratings' may cause permanent damage to the device. In extreme conditions, as with all semiconductors, this may include potentially hazardous rupture of the package. Appropriate safety precautions should always be followed. Exposure to Absolute Maximum Ratings may affect device reliability.

$T_{case} = 25^{\circ}\text{C}$ unless stated otherwise

| Symbol | Parameter | Test Conditions | Max. | Units |
|-------------|-----------------------------------|--|----------|-----------------------|
| V_{CES} | Collector-emitter voltage | $V_{GE} = 0\text{V}$ | 1200 | V |
| V_{GES} | Gate-emitter voltage | - | ± 20 | V |
| I_C | Continuous collector current | $T_{case} = 80^{\circ}\text{C}$ | 200 | A |
| $I_{C(PK)}$ | Peak collector current | 1ms, $T_{case} = 115^{\circ}\text{C}$ | 400 | A |
| P_{max} | Max. transistor power dissipation | $T_{case} = 25^{\circ}\text{C}$, $T_j = 150^{\circ}\text{C}$ | 1435 | W |
| I^2t | Diode I^2t value | $V_R = 0$, $t_p = 10\text{ms}$, $T_{vj} = 125^{\circ}\text{C}$ | 6.25 | kA^2s |
| V_{isol} | Isolation voltage - per module | Commoned terminals to base plate. AC RMS, 1 min, 50Hz | 2500 | V |
| Q_{PD} | Partial discharge - per module | IEC1287. $V_1 = 1300\text{V}$, $V_2 = 1000\text{V}$, 50Hz RMS | 10 | PC |

THERMAL AND MECHANICAL RATINGS

Internal insulation: Al_2O_3
 Baseplate material: Cu
 Creepage distance: 22mm
 Clearance: 12mm
 CTI (Critical Tracking Index): 175

| Symbol | Parameter | Test Conditions | Min. | Typ. | Max. | Units |
|---------------|--|---|------|------|------|------------------------------|
| $R_{th(j-c)}$ | Thermal resistance - transistor (per arm) | Continuous dissipation - junction to case | - | - | 87 | $^{\circ}\text{C}/\text{kW}$ |
| $R_{th(j-c)}$ | Thermal resistance - diode (per arm) (Antiparallel and freewheel diode) | Continuous dissipation - junction to case | - | - | 194 | $^{\circ}\text{C}/\text{kW}$ |
| $R_{th(c-h)}$ | Thermal resistance - case to heatsink (per module) | Mounting torque 5Nm (with mounting grease) | - | - | 15 | $^{\circ}\text{C}/\text{kW}$ |
| T_j | Junction temperature | Transistor | - | - | 150 | $^{\circ}\text{C}$ |
| | | Diode | - | - | 125 | $^{\circ}\text{C}$ |
| T_{stg} | Storage temperature range | - | -40 | - | 125 | $^{\circ}\text{C}$ |
| - | Screw torque | Mounting - M6 | - | - | 5 | Nm |
| | | Electrical connections - M4 | - | - | 2 | Nm |

ELECTRICAL CHARACTERISTICS

T_{case} = 25°C unless stated otherwise.

| Symbol | Parameter | Test Conditions | Min. | Typ. | Max. | Units | |
|-----------------------------------|---|---|----------------|------|------|-------|---|
| I _{CES} | Collector cut-off current | V _{GE} = 0V, V _{CE} = V _{CES} | - | - | 0.25 | mA | |
| | | V _{GE} = 0V, V _{CE} = V _{CES} , T _{case} = 125°C | - | - | 6 | mA | |
| I _{GES} | Gate leakage current | V _{GE} = ±20V, V _{CE} = 0V | - | - | 1 | µA | |
| V _{GE(TH)} | Gate threshold voltage | I _C = 10mA, V _{GE} = V _{CE} | 4.5 | 5.5 | 6.5 | V | |
| V _{CE(sat)} [†] | Collector-emitter saturation voltage | V _{GE} = 15V, I _C = 200A | - | 2.2 | 2.7 | V | |
| | | V _{GE} = 15V, I _C = 200A, T _{case} = 125°C | - | 2.6 | 3.1 | V | |
| I _F | Diode forward current | DC | - | - | 200 | A | |
| I _{FM} | Diode maximum forward current | t _p = 1ms | - | - | 400 | A | |
| V _F [†] | Diode forward voltage (Antiparallel and freewheel diode) | I _F = 200A | - | 2.1 | 2.4 | V | |
| | | I _F = 200A, T _{case} = 125°C | - | 2.1 | 2.4 | V | |
| C _{ies} | Input capacitance | V _{CE} = 25V, V _{GE} = 0V, f = 1MHz | - | 23 | - | nF | |
| L _M | Module inductance - per arm | - | - | 30 | - | nH | |
| R _{INT} | Internal transistor resistance - per arm | - | - | 0.27 | - | mΩ | |
| SC _{Data} | Short circuit. I _{SC} | T _j = 125°C, V _{CC} = 900V, t _p ≤ 10µs, V _{CE(max)} = V _{CES} - L* · di/dt IEC 60747-9 | I ₁ | - | 1375 | - | A |
| | | | I ₂ | - | 1125 | - | A |

Note:

† Measured at the power busbars and not the auxiliary terminals)

L* is the circuit inductance + L_M

ELECTRICAL CHARACTERISTICS
T_{case} = 25°C unless stated otherwise

| Symbol | Parameter | Test Conditions | Min. | Typ. | Max. | Units |
|---------------------|-------------------------------|---|------|------|------|-------|
| t _{d(off)} | Turn-off delay time | $I_C = 200A$ $V_{GE} = \pm 15V$ $V_{CE} = 600V$ $R_{G(ON)} = R_{G(OFF)} = 4.7\Omega$ $L \sim 100nH$ | - | 600 | - | ns |
| t _f | Fall time | | - | 50 | - | ns |
| E _{OFF} | Turn-off energy loss | | - | 20 | - | mJ |
| t _{d(on)} | Turn-on delay time | | - | 240 | - | ns |
| t _r | Rise time | | - | 95 | - | ns |
| E _{ON} | Turn-on energy loss | | - | 25 | - | mJ |
| Q _g | Gate charge | | - | 2 | - | μC |
| Q _{rr} | Diode reverse recovery charge | $I_F = 200A, V_R = 600V,$ $di_F/dt = 2100A/\mu s$ | - | 30 | - | μC |
| I _{rr} | Diode reverse current | | - | 125 | - | A |
| E _{REC} | Diode reverse recovery energy | | - | 13 | - | mJ |

T_{case} = 125°C unless stated otherwise

| Symbol | Parameter | Test Conditions | Min. | Typ. | Max. | Units |
|---------------------|-------------------------------|---|--|------|------|-------|
| t _{d(off)} | Turn-off delay time | $I_C = 200A$ $V_{GE} = \pm 15V$ $V_{CE} = 600V$ $R_{G(ON)} = R_{G(OFF)} = 4.7\Omega$ $L \sim 100nH$ | - | 800 | - | ns |
| t _f | Fall time | | - | 70 | - | ns |
| E _{OFF} | Turn-off energy loss | | - | 27 | - | mJ |
| t _{d(on)} | Turn-on delay time | | - | 385 | - | ns |
| t _r | Rise time | | - | 110 | - | ns |
| E _{ON} | Turn-on energy loss | | - | 40 | - | mJ |
| Q _{rr} | Diode reverse recovery charge | | $I_F = 200A, V_R = 600V,$ $di_F/dt = 1900A/\mu s$ | - | 50 | - |
| I _{rr} | Diode reverse current | - | | 140 | - | A |
| E _{REC} | Diode reverse recovery energy | - | | 20 | - | mJ |

TYPICAL CHARACTERISTICS

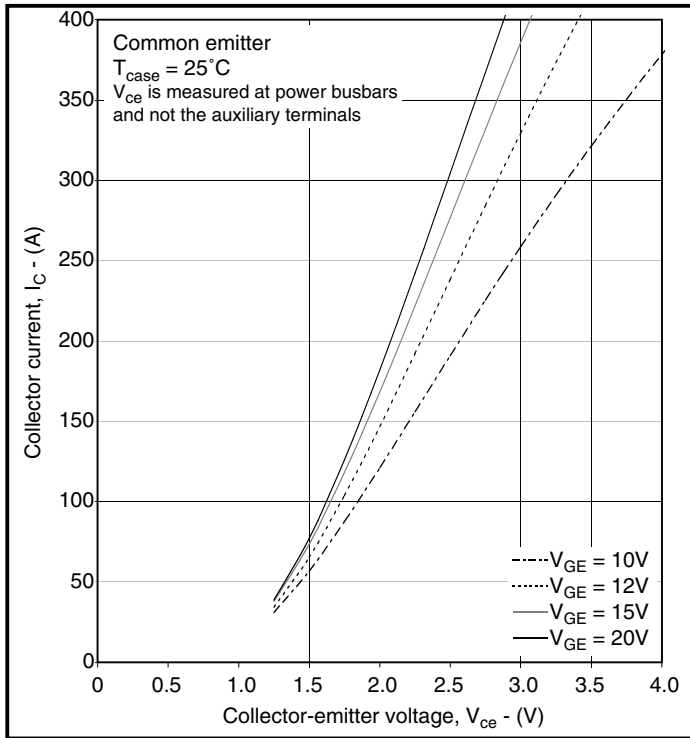


Fig. 3 Typical output characteristics

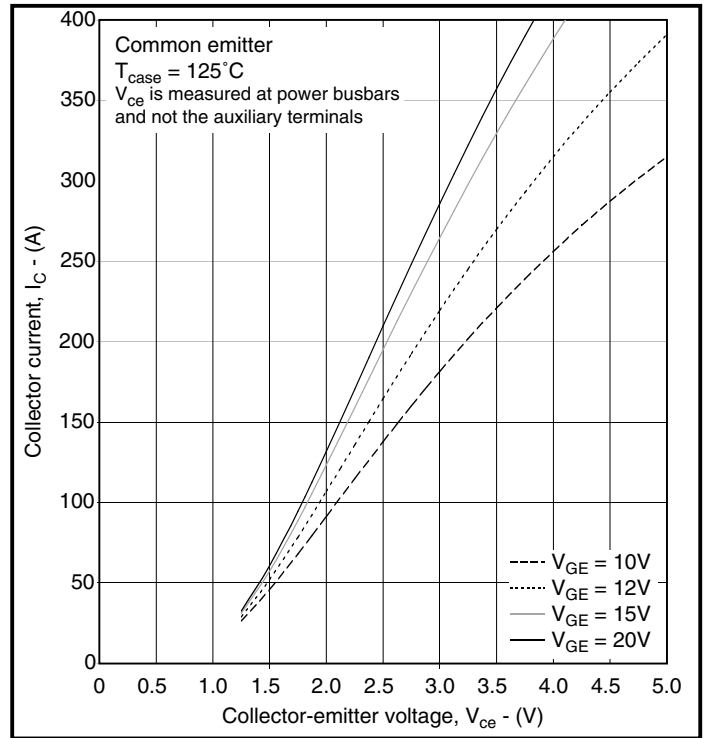


Fig. 4 Typical output characteristics

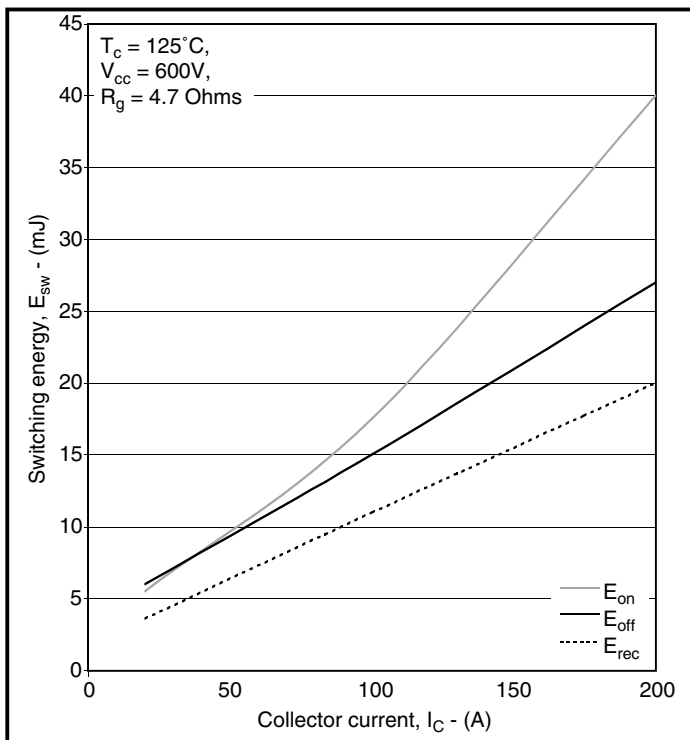


Fig. 5 Typical switching energy vs collector current

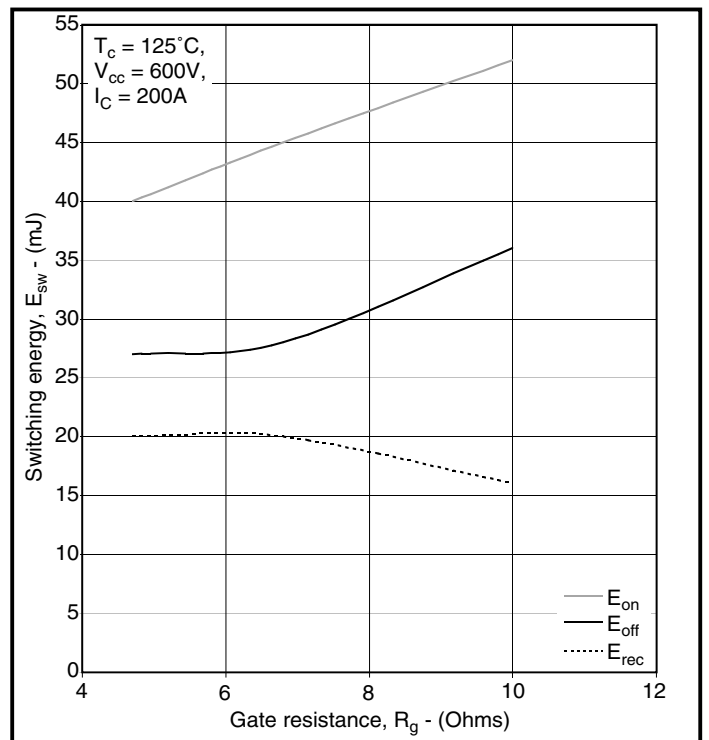


Fig. 6 Typical switching energy vs gate resistance

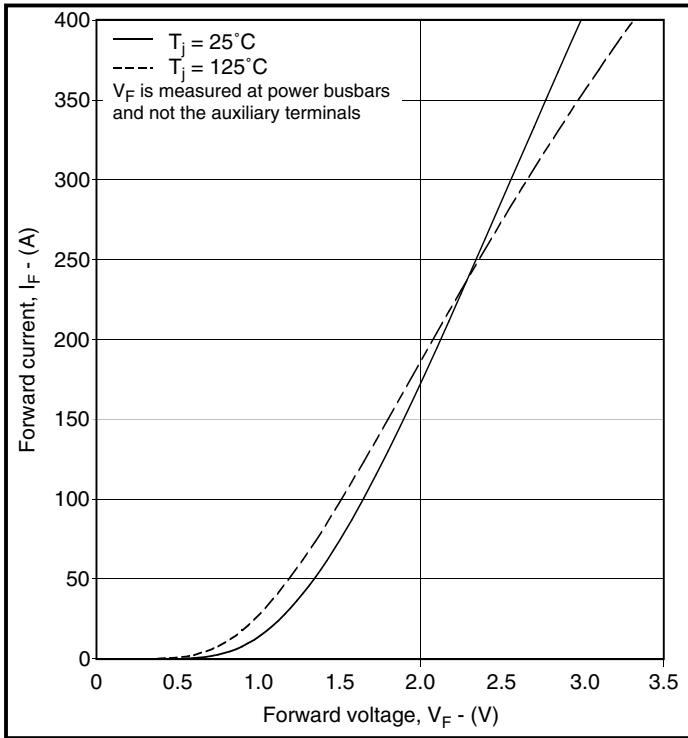


Fig. 7 Diode typical forward characteristics

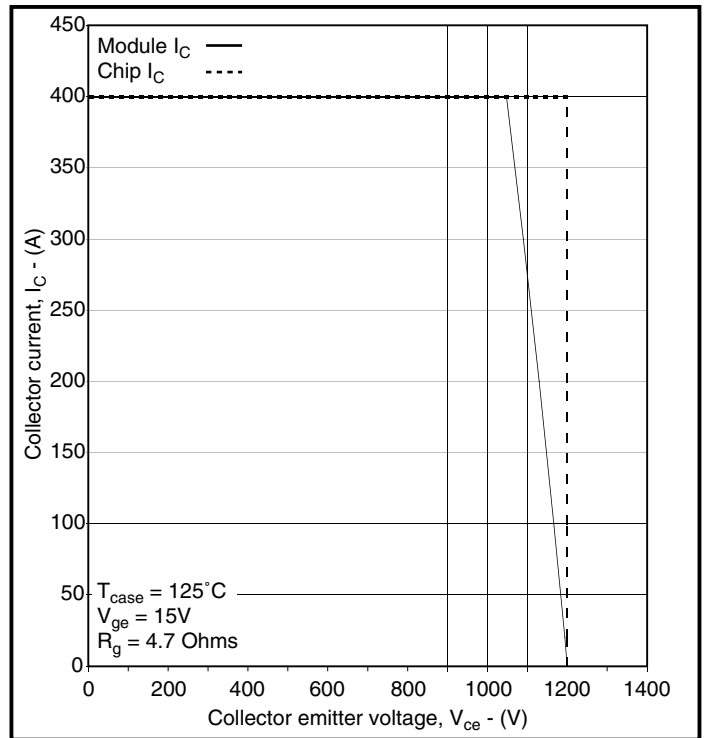


Fig. 8 Reverse bias safe operating area

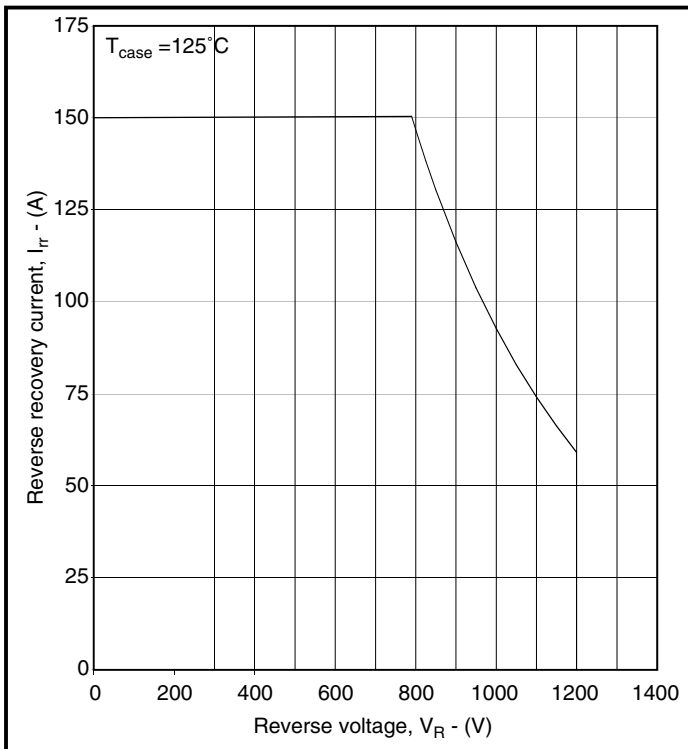


Fig. 9 Diode reverse bias safe operating area

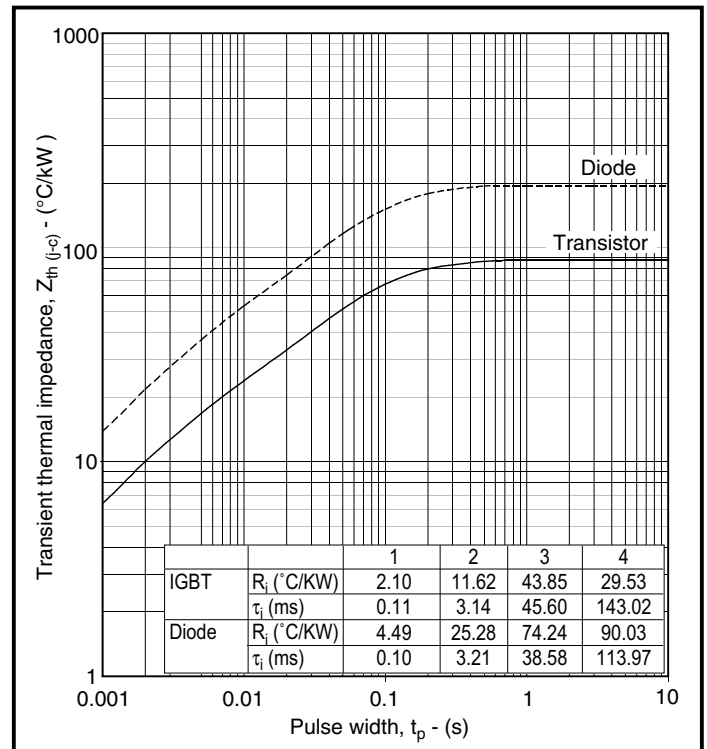


Fig. 10 Transient thermal impedance

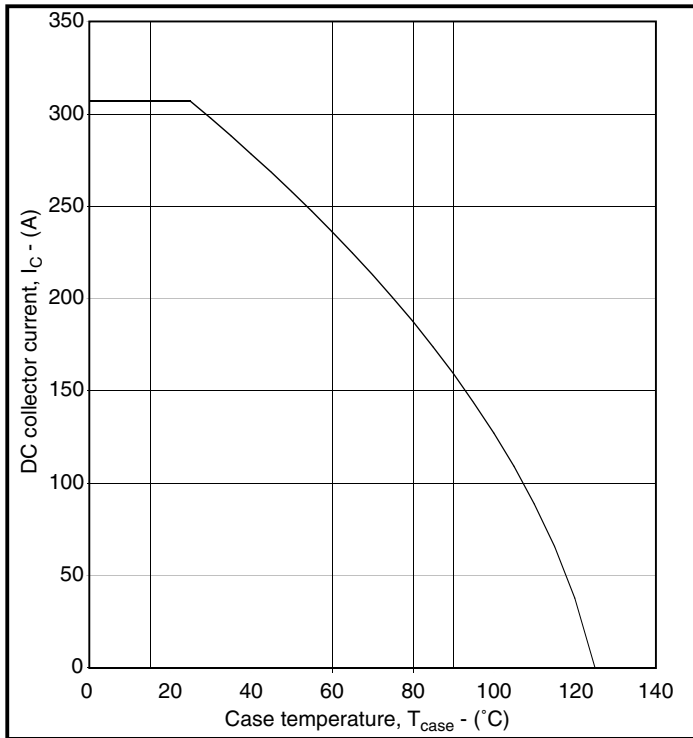
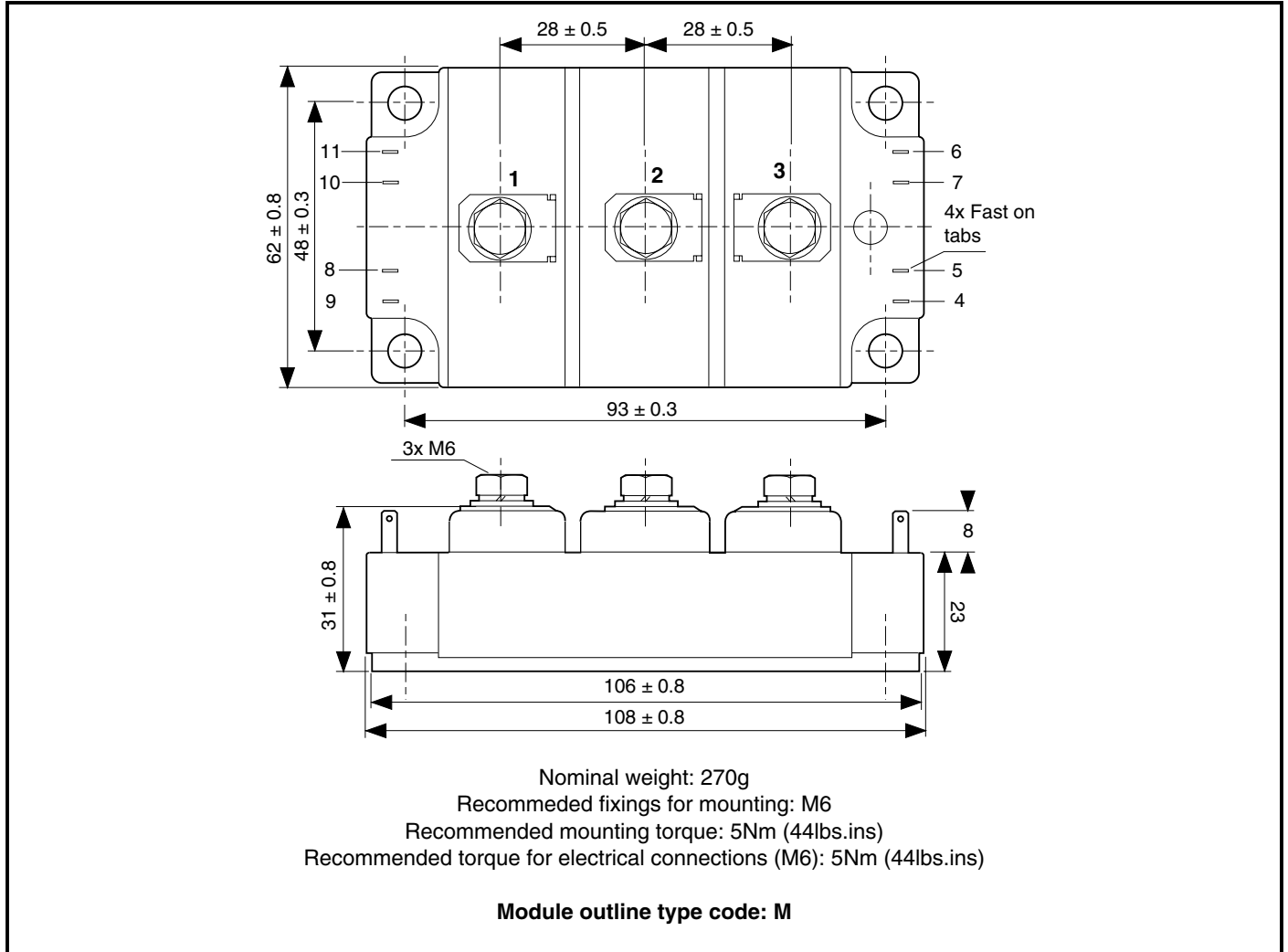


Fig. 11 DC current rating vs case temperature

PACKAGE DETAILS

For further package information please contact Customer Services. All dimensions in mm, unless stated otherwise. DO NOT SCALE.



POWER ASSEMBLY CAPABILITY

The Power Assembly group was set up to provide a support service for those customers requiring more than the basic semiconductor, and has developed a flexible range of heatsink and clamping systems in line with advances in device voltages and current capability of our semiconductors.

We offer an extensive range of air and liquid cooled assemblies covering the full range of circuit designs in general use today. The Assembly group offers high quality engineering support dedicated to designing new units to satisfy the growing needs of our customers.

Using the latest CAD methods our team of design and applications engineers aim to provide the Power Assembly Complete Solution (PACs).

HEATSINKS

The Power Assembly group has its own proprietary range of extruded aluminium heatsinks which have been designed to optimise the performance of Dynex semiconductors. Data with respect to air natural, forced air and liquid cooling (with flow rates) is available on request.

For further information on device clamps, heatsinks and assemblies, please contact your nearest sales representative or Customer Services.



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